

EDAPS 2023 (Hybrid) Call for EDA Solutions

**Sugar Beach Resort, Wolmar, Flic-en-Flac
Republic of Mauritius | Dec. 12 -14th, 2023**

IEEE EDAPS

The IEEE Electrical Design of Advanced Packaging and Systems (**EDAPS**) Symposium is the premier international conference in the Asia-Pacific to share the recent progress of design, modeling, simulation, and measurement related to the electrical issues arising at the chip, package, and system levels. **EDAPS 2023** will be held in **Mauritius, December 12-14, 2023**, covering technical paper presentations, workshops, and keynotes. For further information, please visit edaps.org.

Special Session on EDA Tools:

Turnkey Solutions for Heterogeneous Packaging Design & Modeling

As the benefits of Moore's law reach their fundamental limits, emerging advanced packaging technology is bridging the gap to advance the leading edge of semiconductor technology. While promising advanced packaging has its challenges and complexities. The need for a unified design, modeling, and analysis framework to comprehend the multiscale, multiphysics, and system co-design complex interactions is becoming very critical. To that end, EDAPS 2023 organizing committee invites EDA companies to present their **unique solutions** spanning design, modeling, and analysis for advanced heterogeneous packaging.

The presentation material can be 15 or 30 minutes long; either PPT/PDF/MP3 format will be accepted. Presentations delivery can be either in person or virtually. A participation sponsorship fee of \$500/15min or \$1000/30min presentation will be sought to enable a successful conference.

Important Dates

Confirmation of Participation: September 12th, 2023

Presentation Submission Date: October 12th, 2023

Conference Date: December 12th-14th, 2023